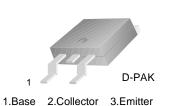
November 2006

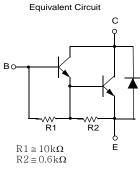


# MJD112 NPN Silicon Darlington Transistor

### Features

- High DC Current Gain
- Built-in a Damper Diode at E-C
- Lead Formed for Surface Mount Applications (No Suffix)





## Absolute Maximum Ratings\* $T_a = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Units	
V <sub>CBO</sub>	Collector-Base Voltage	100	V	
V <sub>CEO</sub>	Collector-Emitter Voltage	100	V	
V <sub>EBO</sub>	Emitter-Base Voltage	5	V	
I <sub>C</sub>	Collector Current (DC)	2	A A	
I <sub>CP</sub>	Collector Current (Pulse)	4		
I <sub>B</sub>	Base Current	50	mA	
P <sub>C</sub>	Collector Dissipation (T <sub>C</sub> =25°C)	20	W	
	Collector Dissipation (T <sub>a</sub> =25°C)	1.75	W	
TJ	Junction Temperature	150	°C	
T <sub>STG</sub>	Storage Temperature	- 65 ~ 150	°C	

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

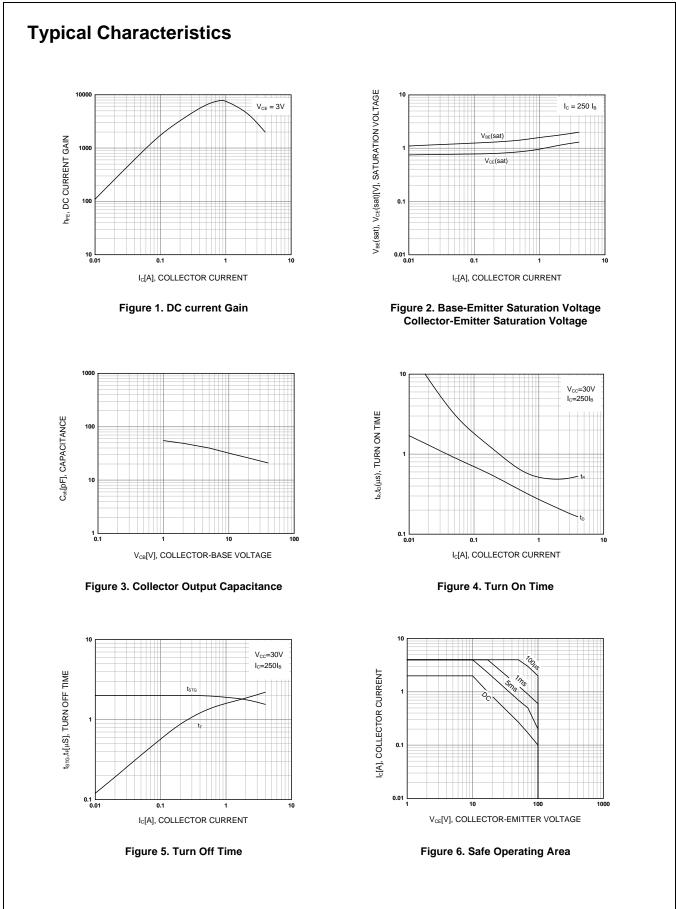
## Electrical Characteristics\* T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
V <sub>CEO</sub> (sus)	Collector-Emitter Sustaining Voltage	I <sub>C</sub> = 30mA, I <sub>B</sub> = 0	100		V
I <sub>CEO</sub>	Collector Cut-off Current	$V_{CE} = 50V, I_B = 0$		20	μΑ
I <sub>CBO</sub>	Collector Cut-off Current	V <sub>CB</sub> = 100V, I <sub>B</sub> = 0		20	μΑ
I <sub>EBO</sub>	Emitter Cut-off Current	$V_{EB} = 5V, I_{C} = 0$		2	mA
h <sub>FE</sub>	* DC Current Gain	$V_{CE} = 3V, I_C = 0.5A$ $V_{CE} = 3V, I_C = 2A$ $V_{CE} = 3V, I_C = 4A$	500 1000 200	12K	
V <sub>CE</sub> (sat)	* Collector-Emitter Saturation Voltage	$I_{C} = 2A, I_{B} = 8mA$ $I_{C} = 4A, I_{B} = 40mA$		2 3	V V
V <sub>BE</sub> (sat)	* Base-Emitter Saturation Voltage	I <sub>C</sub> = 4A, I <sub>B</sub> = 40mA		4	V
V <sub>BE</sub> (on)	* Base-Emitter On Voltage	V <sub>CE</sub> = 3A, I <sub>C</sub> = 2A		2.8	V
f <sub>T</sub>	Current Gain Bandwidth Product	V <sub>CE</sub> = 10V, I <sub>C</sub> = 0.75A	25		MHz
C <sub>ob</sub>	Output Capacitance	$V_{CB} = 10V, I_E = 0$ f = 0.1MHz		100	pF

\* Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%

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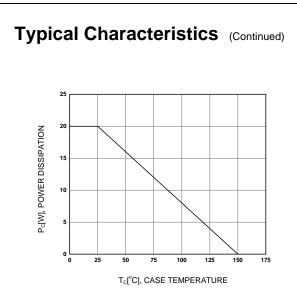
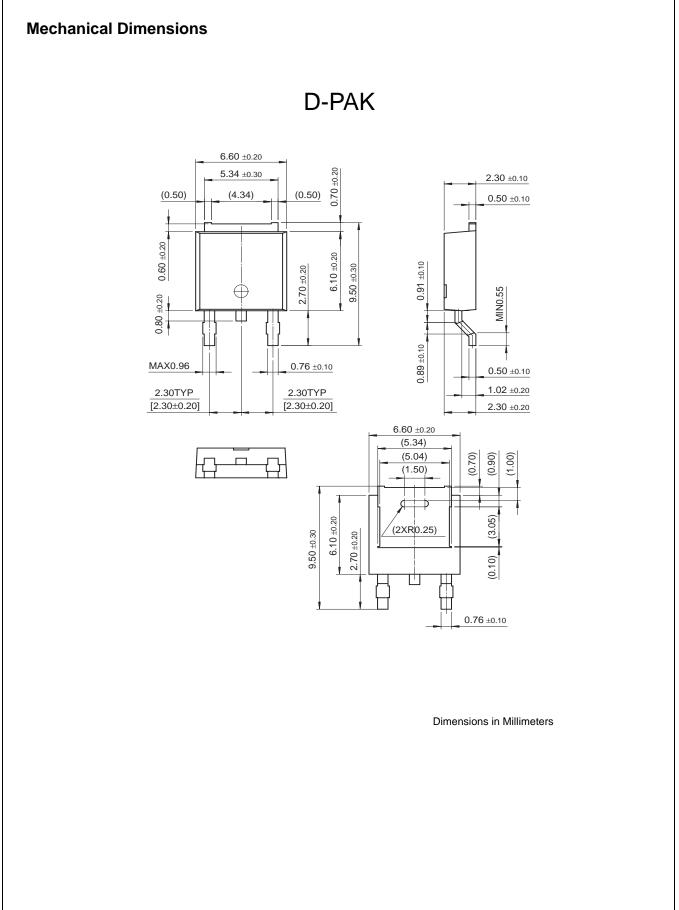


Figure 1. Power Derating





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MJD112 NPN Silicon Darlington Transistor

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